

# HSMS-282Z

## RF Schottky Barrier Diodes In Surface Mount SOD-323 Package



### Data Sheet

#### Description/Applications

Avago Technologies's HSMS-282Z is a RF Schottky Barrier Diode, featuring low series resistance, low forward voltage at all current levels and good RF characteristics.

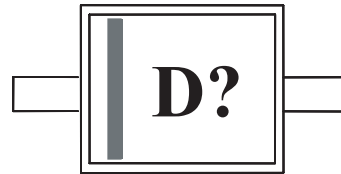
It is housed in a low cost, industrial standard surface mount package - SOD-323. This package offers customer who already use SOT-23 and SOT-323 packages, a logical transition to a smaller package outline to accommodate end product design with limited board space.

The HSMS-282Z is specially designed for both analog and digital applications. The typical applications are mixing, detecting, switching, sampling, clamping and wave shaping.

#### Features

- 2 Leads Surface Mount Package
- Low Turn-On Voltage
- Low Series Resistance
- Microwave Frequency Operation
- Tape and Reel Options Available
- Low Failure in Time (FIT) Rate
- MSL1 & Lead Free

#### Package Marking and Pin Connections



Note: Package marking provides orientation and identification  
"D" = Device Code  
"?" = Month code indicates the month of manufacture

Table 1. Absolute Maximum Ratings [1] at Tc = +25°C

| Symbol           | Parameter                    | Unit | Max Rating |
|------------------|------------------------------|------|------------|
| I <sub>f</sub>   | Forward Current (1 μs Pulse) | Amp  | 1          |
| P <sub>IV</sub>  | Peak Inverse Voltage         | V    | 15         |
| T <sub>j</sub>   | Junction Temperature         | °C   | 150        |
| T <sub>stg</sub> | Storage Temperature          | °C   | -60 to 150 |
| θ <sub>jc</sub>  | Thermal Resistance [2]       | °C/W | 135        |

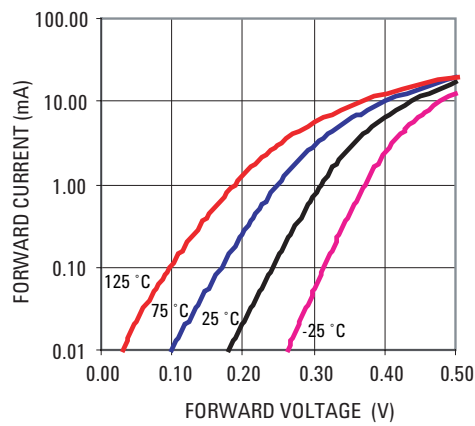
Notes:

1. Operation in excess of any one of these conditions may result in permanent damage to the device.
2. Thermal Resistance is measured from junction to board using IR method.

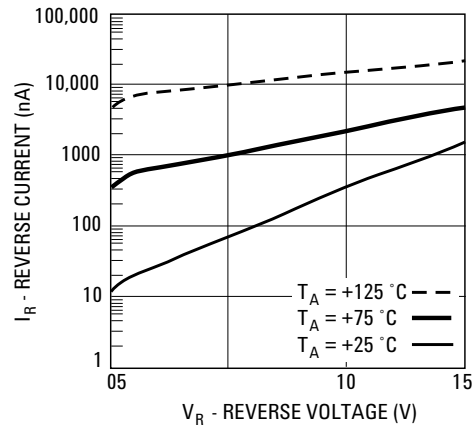
**Table 2. Electrical Specifications at Tc = +25°C**

|                 | Minimum Breakdown Voltage V <sub>BR</sub> (V)                      | Maximum Forward Voltage V <sub>F</sub> (mV) | Maximum Forward Voltage V <sub>F</sub> (V) | Maximum Reverse Leakage I <sub>R</sub> (nA) | Minimum Capacitance C <sub>T</sub> (pF) | Typical Dynamic Resistance R <sub>D</sub> (Ohm) |
|-----------------|--|---|--|---|---|---|
|                 | 15   | 340   | 0.5  | 100   | 1.0                                     | 12  |
| Test Conditions | V <sub>R</sub> = V <sub>BR</sub><br>Measure I <sub>R</sub> ≤ 100uA | I <sub>F</sub> = 1mA                        | I <sub>F</sub> = 10mA                      | V <sub>R</sub> = 1V                         | V <sub>R</sub> = 0 V<br>f = 1 MHz       | I <sub>F</sub> = 5mA                            |

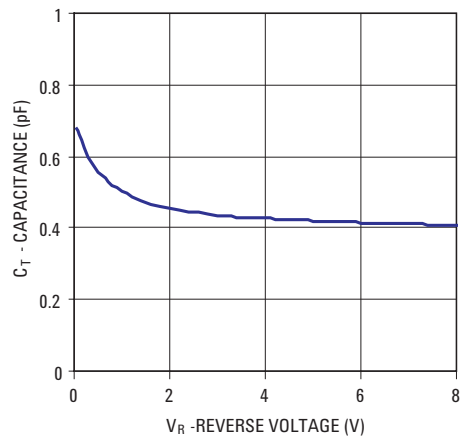
**Typical Performance Curves at Tc = +25°C**



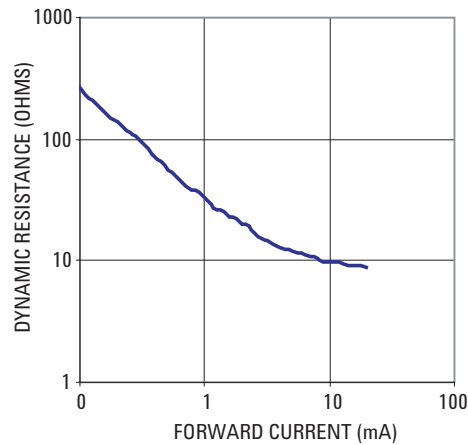
**Figure 1. Forward Current vs. Forward Voltage**



**Figure 2. Reverse Current vs. Reverse Voltage**



**Figure 3. Total Capacitance vs. Reverse Bias**



**Figure 4. Dynamic Resistance vs. Forward Current**

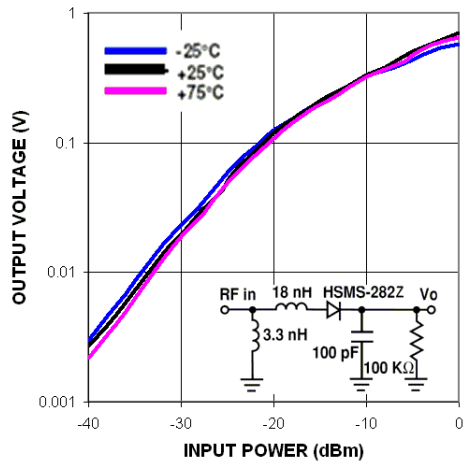


Figure 5. Typical Output Voltage vs. Input Power, Small Signal Detector operating at 850 MHz

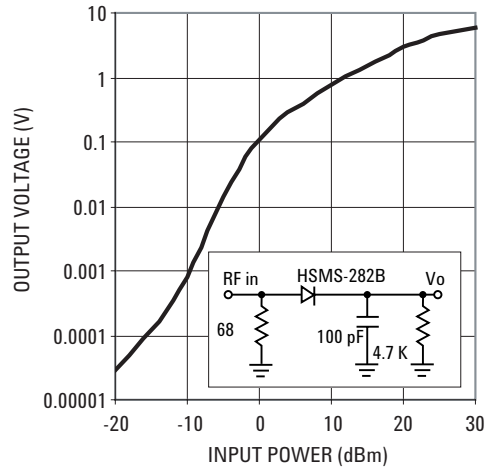
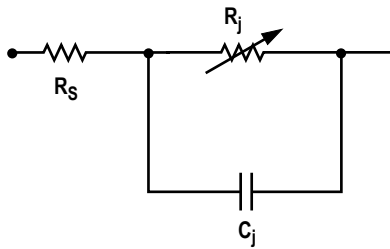


Figure 6. Typical Output Voltage vs. Input Power, Large Signal Detector Operating at 915 MHz.

### Linear Equivalent Circuit Model Diode Chip



$R_S$  = series resistance (see Table of SPICE parameters)

$C_j$  = junction capacitance (see Table of SPICE parameters)

$$R_j = \frac{8.33 \times 10^{-5} \text{ nT}}{I_b + I_s}$$

where

$I_b$  = externally applied bias current in amps

$I_s$  = saturation current (see table of SPICE parameters)

$T$  = temperature, K

$n$  = ideality factor (see table of SPICE parameters)

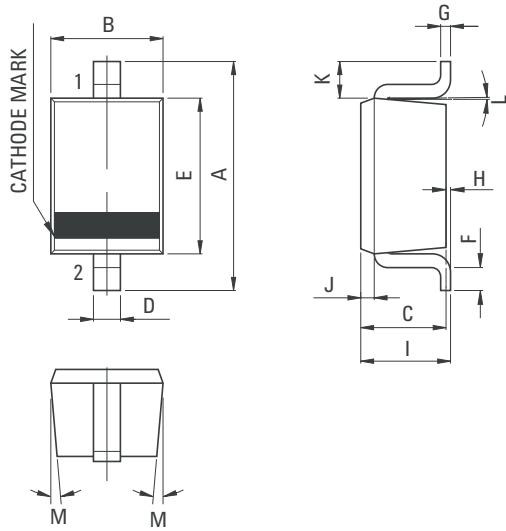
Note:

To effectively model the packaged HSMS-282x product, please refer to Application Note AN1124.

### SPICE Parameters

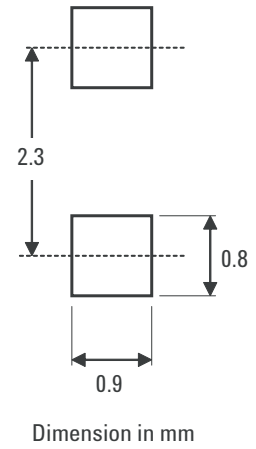
| Parameter | Units    | HSMS-282Z |
|-----------|----------|-----------|
| $B_V$     | V        | 15        |
| $C_{J0}$  | pF       | 0.7       |
| $E_G$     | eV       | 0.69      |
| $I_{BV}$  | A        | 1E-4      |
| $I_S$     | A        | 2.2E-8    |
| $N$       |          | 1.08      |
| $R_S$     | $\Omega$ | 6.0       |
| $P_B$     | V        | 0.65      |
| $P_T$     |          | 2         |
| $M$       |          | 0.5       |

### Package Outline and Dimension

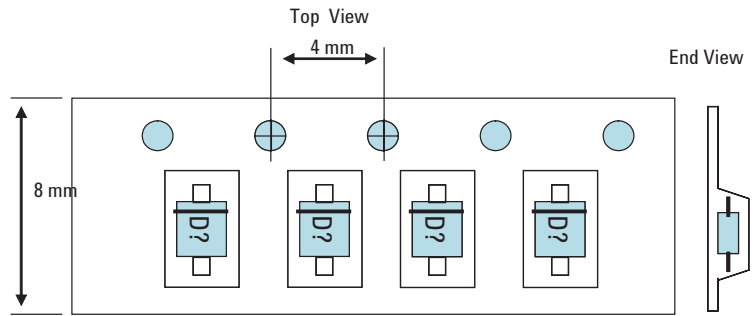
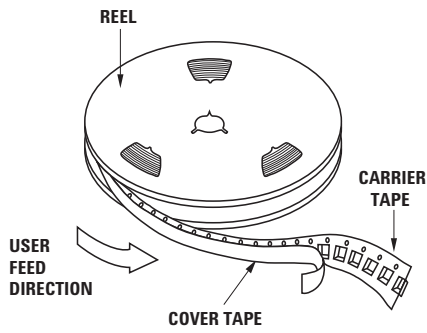


| DIM | MILLIMETERS     |
|-----|-----------------|
| A   | 2.50 ± 0.2      |
| B   | 1.25 ± 0.05     |
| C   | 0.90 ± 0.05     |
| D   | 0.30+0.06/-0.04 |
| E   | 1.70 ± 0.05     |
| F   | MIN 0.17        |
| G   | 0.126 ± 0.03    |
| H   | 0~0.1           |
| I   | 1.0 MAX         |
| J   | 0.15 ± 0.05     |
| K   | 0.4             |
| L   | 2°+4/-2         |
| M4  | ~6°             |

### PCB Footprint

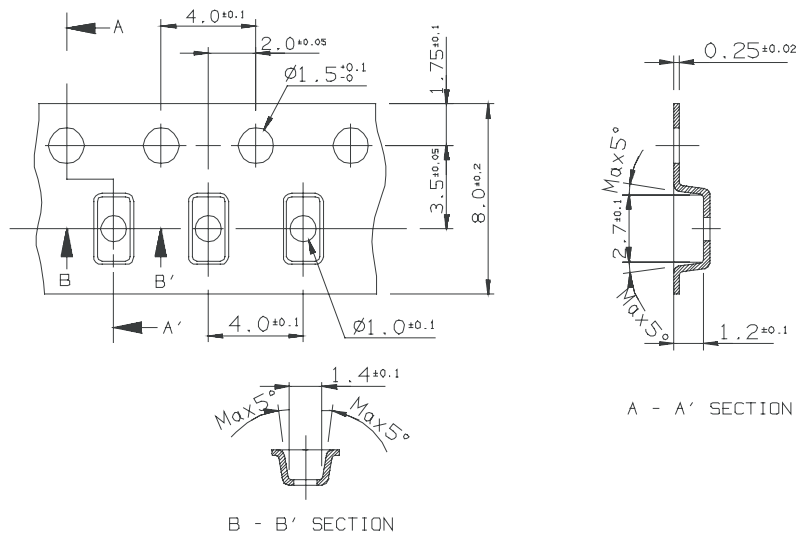


### Device Orientation



Note: "D" represents package marking code  
 "?" represents date code

## Tape Dimensions



Specification < Unit: mm >

A. hole pitch : 50 Pitch Tolerance :  $200 \pm 0.3$

## Order Information

| Part Number    | No. of Units | Container       |
|----------------|--------------|-----------------|
| HSMS-282Z-BLKG | 100          | Anti-static bag |
| HSMS-282Z-TR1G | 3000         | 7" reel         |

For product information and a complete list of distributors, please go to our web site: [www.avagotech.com](http://www.avagotech.com)

Avago, Avago Technologies, and the A logo are trademarks of Avago Technologies in the United States and other countries. Data subject to change. Copyright © 2005-2008 Avago Technologies. All rights reserved. Obsoletes 5989-4733EN AV02-0147EN - June 25, 2008

**AVAGO**  
TECHNOLOGIES